



All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	0°C to +65°C	----
Storage Temperature	-20°C to +85°C	----
Stabilization Bake	125°C, 24 hours (Non-operating)	----
Thermal Shock	0°C to +85°C 15 min dwell at extreme temperatures, 1 min transfer 250 cycles	MIL-STD-202, Method 107
Humidity Storage	Temp: 85°C, Humidity: 85% RH, Non-operating for 1000 Hrs.	----
Dc Burn In	Ambient Conditions with Bias. Bias Conditions: +65V ~40mA 500 Hrs.	----
Thermal Imaging	Unit setup to deliver 15W at 27MHz. Thermal images captured at 20°C and 65°C baseplate temperature with CW RF power for 10 Mins	----
ESD Gun Contact	Air Discharge: ±2.0 kV, ±4.0 kV, ±8.0 kV. Contact Discharge: ±2.0 kV, ±4.0 kV, ± 6.0 kV, ±8.0Kv Non-operating Condition. 10 positive & 10 negative charges at each location	IEC 61000-4-2
ESD HBM Test	Tested up to ± 1000V	JS-001
FedEx Transit Test (Packaging)	Test performed on packaged unit. Pre-conditioning + Shock (20 drops, 30 inches) + Compression (261 lb, 0.05" deflection) + Vibration (90 min random Vibration)	ISTA 6-FEDEX-A TEST